

CHEE LIP GAN

Curriculum Vitae

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Education:

- Ph.D. (Advanced Materials for Micro- and Nano-Systems) – Singapore-MIT Alliance (National University of Singapore) - 2003
- B.Eng (Electrical) 1st class honours – National University of Singapore – 1999

Professional Experience:

- 1 Apr 2010 – now, Associate Professor, School of Materials Engineering, Nanyang Technological University
- 1 Jul 2008 – 30 June 2010, SMA Visiting Scientist, Massachusetts Institute of Technology, USA (concurrent appt)
- 21 Aug 2007 – 20 Aug 2009, Faculty Associate, Institute of Microelectronics, Singapore (concurrent appt)
- 1 Jun 2006 – 31 May 2008, Assistant Chair (Alumni & Graduates), MSE, NTU (concurrent appt)
- 1 Jul 2005 – 30 Jun 2010, Singapore-MIT Alliance Fellow, Advanced Materials for Micro- and Nano-Systems, SMA (concurrent appt)
- 2 Jul 2003 – 31 Mar 2010, Assistant Professor, School of Materials Engineering, Nanyang Technological University

Professional Qualifications/Memberships:

- IEEE Senior Member (2009 – now)
- ACS Member (2009 – now)
- MRS Member (2002 – now)
- IEEE Member (1998 – 2009)

Awards:

- Best Paper in Reliability at the 15th International Symposium on the Physical & Failure Analysis of Integrated Circuits (July, 2008)
- 2003 MRS Spring Meeting Graduate Student Award – Silver Award (April, 2003)
- Best Paper in Reliability at the 9th International Symposium on the Physical & Failure Analysis of Integrated Circuits (July, 2002)

Service to professional bodies:

- IEEE Rel/CPMT/ED Chapter Executive Committee (Vice-Chairman, 01/01/09 – 31/12/2010; Treasurer, 01/01/07 – 31/12/08; Member, 01/02/04 – 31/12/06)
- International Symposium on the Physical & Failure Analysis of Integrated Circuits (IPFA) Organizing Committee (General Chair, 09-10; General Co-Chair, 08-09; Technical Programme Chair, 07-08; Technical Programme Co-Chair, 05-07; Member, 04-05)
- Asia program committee member of 2009 IEEE International Interconnect Technology Conference, Sapporo, Japan, (2008 – now)
- Associate Editor of IEEE Transactions on Device and Materials Reliability (2006-2008)
- Symposium organizer, MRS Spring Meeting 2008, Symposium N - Materials and Processes for Advanced Interconnects for Microelectronics, March 2008.
- Reviewer of journals such as IEEE Electron Device Letters, IEEE Transactions on Electron Devices, IEEE Transactions on Device and Materials Reliability, Applied Physics Letter, Journal of Electronic Materials, Nanotechnology, Thin Solid Films, Journal of Electrochemical Society